

Discontinuation in automotive TOPLED E1608 portfolio

Customer Info Package for:

OS-PDN-2023-035: Discontinuation of InGaAlP classic chip technology

Status: May 2023

TOPLED E1608: Discontinuation of InGaAlP classic chip technology

Motivation and Impact

Motivation

- Focus on high volume devices with InGaAlP Thinfilm chip technology
- Harmonization of the polarity across the TOPLED E1608 portfolio
- **Continuous supply until 2028 ensured**

Affected Devices:

TOPLED E1608	
Low brightness	Mid brightness
KG DELLS1.22	KP DELMS1.22
KY DELLS1.22	KG DELMS1.22
KO DELLS1.22	KY DELMS1.22
KS DELLS1.22	KO DELMS1.22
	KR DELMS1.22
	KS DELMS1.22

TOPLED E1608: Discontinuation of InGaAlP classic chip technology

Replacements and Timeline

Product Discontinuation (PDN):
PDN publication: 15.05.2023
Last order (LTO): 31.01.2025
Last delivery (LTD): 31.01.2028

OS-PDN-2023-035

PDN Products

TOPLED E1608
KP DELMS1.12
KG DELLS1.12
KG DELMS1.12

KY DELLS1.22
KO DELLS1.22
KS DELLS1.22

KY DELMS1.22
KO DELMS1.22
KR DELMS1.22
KS DELMS1.22

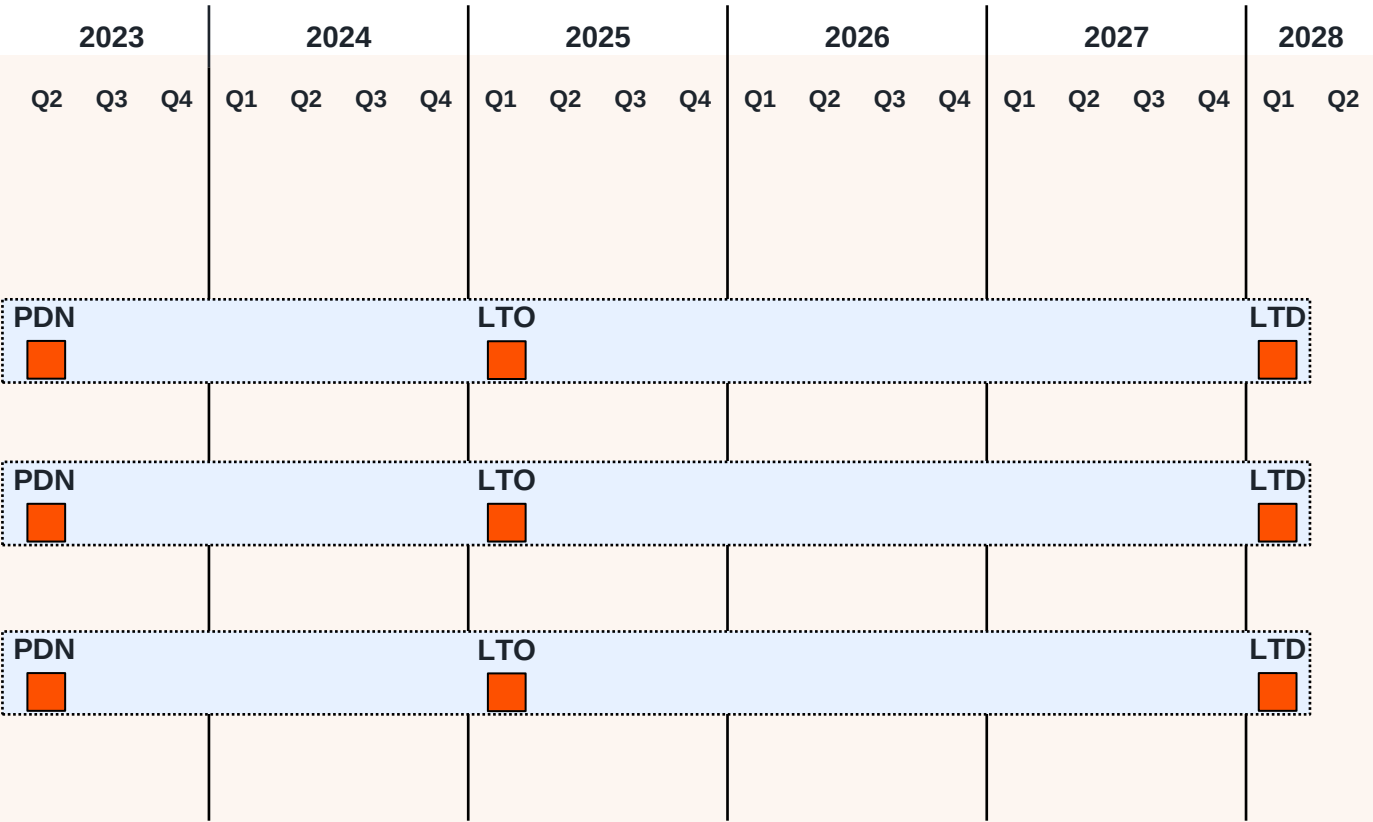
Replacements

TOPLED E1608
KP DELPS1.FP*
KT DELQS1.12*
KT DELQS1.12*

KY DELPS1.22 @5mA*
KO DELPS1.22 @5mA*
KR DELPS1.22 @5mA*

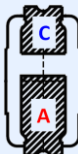
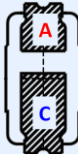
KY DELPS1.22 @5mA
KO DELPS1.22 @5mA
KR DELPS1.22 @5mA
KS DELPS1.22 @5mA

* different spectrum
and/or brightness level



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Introduction of lower binning current of 5mA into existing TOPLED E1608 Thinfilm devices

Datasheet	Samples* ¹	PPAP* ²	SOP* ²
available	available	Ready	Ready
Technical Details & Target Performance			Package & Design
KY DELPS1.22 to replace KY DELMS1.22	Binning Current 5 mA	Ordering Code Q65113A6171	• Change to known Thinfilm chip technology • Package marking and orientation in tape will be similar • Package polarity changes Please see Application Note for TOPLED E1608
KS DELPS1.22 to replace KS DELMS1.22	5 mA	Q65113A6170	
KR DELPS1.22 to replace KR DELMS1.22	5 mA	Q65113A6176	
KO DELPS1.22 to replace KO DELMS1.22	5 mA	Q65113A6177	
			Highlights & Benefits • Thinfilm chip offers supply security and an efficiency gain • Qualifications: AEC-Q102 Qualified • Consistent polarity for portfolio • Increased binning variety for Thinfilm devices (5 and 20mA)
			
Package Size [mm]	Identical for replacement		
Solder Pad	Identical for replacement		

*¹ extended lead time to be considered for specific binning selections

*² ready for PPAP and SOP depending on customer request

Sensing is life

